

Title (en)  
ELECTROMAGNETIC RELAY

Title (de)  
ELEKTROMAGNETISCHES RELAIS

Title (fr)  
RELAIS ÉLECTROMAGNÉTIQUE

Publication  
**EP 2650900 B1 20190116 (EN)**

Application  
**EP 11847440 A 20110323**

Priority  
• JP 2010271826 A 20101206  
• JP 2011057001 W 20110323

Abstract (en)  
[origin: EP2650900A1] The objective of the present invention is to provide an electromagnetic relay, wherein the number of parts and the number of assembly processes are few, dispersion in the operation characteristics thereof do not tend to be generated, and which has excellent current-supplying characteristic. In order to achieve this objective, the electromagnetic relay makes a plate-shaped pivoting piece (32), one end of which is supported in cantilever state, pivoted by a movable block (40), which reciprocates in the up-down direction on the basis of excitation and demagnetization of an electromagnet block (20) housed within a housing (10), and makes a movable contact (34) formed on the other end of the plate-shaped pivoting piece (32) make/break contact with an anchored contact (36) formed on the tip section of an anchored contact terminal (35). In particular, the one-end section of the plate-shaped pivoting piece (32) is supported pivotably in cantilever state by the upper end section of a movable contact terminal (31), with a support spring (33) comprising a conductive sheet spring material interposed therebetween.

IPC 8 full level  
**H01H 50/34** (2006.01); **H01H 50/54** (2006.01); **H01H 50/64** (2006.01)

CPC (source: EP US)  
**H01H 50/641** (2013.01 - EP US); **H01H 51/06** (2013.01 - US); **H01H 51/2209** (2013.01 - EP US); **H01H 50/14** (2013.01 - EP US); **H01H 50/548** (2013.01 - EP US); **H01H 2051/2218** (2013.01 - EP US)

Designated contracting state (EPC)  
AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO RS SE SI SK SM TR

DOCDB simple family (publication)  
**EP 2650900 A1 20131016**; **EP 2650900 A4 20170426**; **EP 2650900 B1 20190116**; CN 103229266 A 20130731; CN 103229266 B 20150930; JP 2012123944 A 20120628; JP 4952840 B1 20120613; US 2014043120 A1 20140213; US 8963660 B2 20150224; WO 2012077362 A1 20120614

DOCDB simple family (application)  
**EP 11847440 A 20110323**; CN 201180057207 A 20110323; JP 2010271826 A 20101206; JP 2011057001 W 20110323; US 201113989049 A 20110323